

Day : Wednesday

Date: 9/7/2005
Time: 16:02:47**Inventor Name Search Result**

Your Search was:

Last Name = HEDLER

First Name = HARRY

Application#	Patent#	Status	Date Filed	Title	Inventor Name
<u>08450959</u>	Not Issued	161	05/23/1995	THERMOELECTRIC RECEIVER COMPONENT FOR INFRARED AND VISIBLE RADIATION WITH HIGH DIRECTIVITY AND SELECTIVITY	HEDLER, HARRY
<u>09509228</u>	Not Issued	161	09/13/2000	Method for producing a multilevel carrier (substrate), especially for multichip modules	HEDLER, HARRY
<u>09658713</u>	<u>6406937</u>	150	09/11/2000	METHOD FOR PRODUCING AN ELECTRICAL CONNECTION BETWEEN THE FRONT AND REAR SIDES OF SEMICONDUCTOR CHIPS	HEDLER, HARRY
<u>09806401</u>	Not Issued	161	10/22/2001	Electronic module, especially a multichip module, with multi-layer metallization and corresponding production method	HEDLER, HARRY
<u>09944796</u>	<u>6664176</u>	150	08/31/2001	PAD- REROUTING FOR INTEGRATED CIRCUIT CHIPS	HEDLER, HARRY
<u>10022226</u>	Not Issued	94	12/17/2001	ELECTRONIC COMPONENT WITH FLEXIBLE BONDING PADS AND METHOD OF PRODUCING SUCH A COMPONENT	HEDLER, HARRY
<u>10022606</u>	<u>6555415</u>	150	12/17/2001	ELECTRONIC CONFIGURATION WITH FLEXIBLE BONDING PADS	HEDLER, HARRY
<u>10032941</u>	<u>6888256</u>	150	10/31/2001	COMPLIANT RELIEF WAFER LEVEL PACKAGING	HEDLER, HARRY
<u>10044000</u>	<u>6727576</u>	150	10/31/2001	TRANSFER WAFER LEVEL PACKAGING	HEDLER, HARRY
<u>10044136</u>	<u>6638870</u>	150	01/10/2002	FORMING A STRUCTURE ON A WAFER	HEDLER, HARRY

<u>10051543</u>	Not Issued	160	01/22/2002	Transfer wafer level packaging	HEDLER, HARRY
<u>10056356</u>	6858799	150	01/24/2002	ELECTRONIC COMPONENT WITH A SEMICONDUCTOR CHIP AND METHOD OF PRODUCING THE ELECTRONIC COMPONENT	HEDLER, HARRY
<u>10105467</u>	6852931	150	03/26/2002	CONFIGURATION HAVING AN ELECTRONIC DEVICE ELECTRICALLY CONNECTED TO A PRINTED CIRCUIT BOARD	HEDLER, HARRY
<u>10132826</u>	Not Issued	41	04/25/2002	Electronic component with semiconductor chips, electronic assembly composed of stacked semiconductor chips, and methods for producing an electronic component and an electronic assembly	HEDLER, HARRY
<u>10135273</u>	6861291	150	04/30/2002	METHOD PRODUCING A CONTACT CONNECTION BETWEEN A SEMICONDUCTOR CHIP AND A SUBSTRATE AND THE CONTACT CONNECTION	HEDLER, HARRY
<u>10155337</u>	6756540	150	05/24/2002	SELF-ADHERING CHIP	HEDLER, HARRY
<u>10157175</u>	6826037	150	05/29/2002	ELECTRONIC STRUCTURE	HEDLER, HARRY
<u>10159848</u>	6744127	150	05/31/2002	SEMICONDUCTOR CHIP, MEMORY MODULE AND METHOD FOR TESTING THE SEMICONDUCTOR CHIP	HEDLER, HARRY
<u>10179751</u>	6630723	150	06/25/2002	LASER PROGRAMMING OF INTEGRATED CIRCUITS	HEDLER, HARRY
<u>10195958</u>	6864575	150	07/16/2002	ELECTRONIC INTERFACE STRUCTURES AND METHODS	HEDLER, HARRY
<u>10205081</u>	6851598	150	07/25/2002	ELECTRONIC COMPONENT WITH A SEMICONDUCTOR CHIP AND METHOD FOR PRODUCING THE ELECTRONIC COMPONENT	HEDLER, HARRY
<u>10236895</u>	6807064	150	09/06/2002	ELECTRONIC COMPONENT WITH AT LEAST ONE SEMICONDUCTOR CHIP AND	HEDLER, HARRY

				METHOD FOR PRODUCING THE ELECTRONIC COMPONENT	
<u>10252449</u>	<u>6936928</u>	150	09/23/2002	SEMICONDUCTOR COMPONENT AND METHOD FOR ITS PRODUCTION	HEDLER, HARRY
<u>10260872</u>	<u>6897568</u>	150	09/30/2002	ELECTRONIC COMPONENT WITH FLEXIBLE CONTACTING PADS AND METHOD FOR PRODUCING THE ELECTRONIC COMPONENT	HEDLER, HARRY
<u>10284649</u>	<u>6919232</u>	150	10/31/2002	PROCESS FOR PRODUCING A SEMICONDUCTOR CHIP	HEDLER, HARRY
<u>10285924</u>	<u>6714418</u>	150	11/01/2002	METHOD FOR PRODUCING AN ELECTRONIC COMPONENT HAVING A PLURALITY OF CHIPS THAT ARE STACKED ONE ABOVE THE OTHER AND CONTACT-CONNECTED TO ONE ANOTHER	HEDLER, HARRY
<u>10298772</u>	Not Issued	41	11/18/2002	Process for producing a component module	HEDLER, HARRY
<u>10298837</u>	<u>6845554</u>	150	11/18/2002	METHOD FOR CONNECTION OF CIRCUIT UNITS	HEDLER, HARRY
<u>10336373</u>	Not Issued	71	01/03/2003	Method of producing semiconductor chips with a chip edge guard, in particular for wafer level packaging chips	HEDLER, HARRY
<u>10440480</u>	<u>6897088</u>	150	05/15/2003	METHOD FOR CONNECTING CIRCUIT DEVICES	HEDLER, HARRY
<u>10446396</u>	Not Issued	93	05/28/2003	CONNECTION OF INTEGRATED CIRCUITS	HEDLER, HARRY
<u>10464429</u>	<u>6916185</u>	150	06/18/2003	CONNECTION OF INTEGRATED CIRCUIT TO A SUBSTRATE	HEDLER, HARRY
<u>10477967</u>	Not Issued	20	05/10/2004	Method for producing an electronic component, especially a memory chip	HEDLER, HARRY
<u>10625495</u>	<u>6887777</u>	150	07/23/2003	METHOD FOR CONNECTING AN INTEGRATED CIRCUIT TO A SUBSTRATE AND CORRESPONDING CIRCUIT ARRANGEMENT	HEDLER, HARRY
<u>10630632</u>	Not	95	07/29/2003	SEMICONDUCTOR CIRCUIT	HEDLER, HARRY

	Issued			MODULE AND METHOD FOR FABRICATING SEMICONDUCTOR CIRCUIT MODULES	
<u>10634242</u>	<u>6905954</u>	150	08/05/2003	METHOD FOR PRODUCING A SEMICONDUCTOR DEVICE AND CORRESPONDING SEMICONDUCTOR DEVICE	HEDLER, HARRY
<u>10637899</u>	<u>6927157</u>	150	08/08/2003	INTEGRATED CIRCUIT AND METHOD FOR PRODUCING A COMPOSITE COMPRISING A TESTED INTEGRATED CIRCUIT AND AN ELECTRICAL DEVICE	HEDLER, HARRY
<u>10642063</u>	Not Issued	95	08/15/2003	METHOD OF PRODUCING A SEMICONDUCTOR COMPONENT HAVING A COMPLIANT BUFFER LAYER	HEDLER, HARRY
<u>10642092</u>	Not Issued	71	08/15/2003	Method for fabricating connection regions of an integrated circuit, and integrated circuit having connection regions	HEDLER, HARRY
<u>10721745</u>	Not Issued	41	11/26/2003	Method for producing an integrated circuit with a rewiring device and corresponding integrated circuit	HEDLER, HARRY
<u>10721787</u>	Not Issued	71	11/26/2003	Semiconductor component and method for producing same	HEDLER, HARRY
<u>10747670</u>	Not Issued	71	12/30/2003	Method for connecting an integrated circuit to a substrate and corresponding arrangement	HEDLER, HARRY
<u>10754172</u>	Not Issued	71	01/09/2004	CARRIER FOR RECEIVING AND ELECTRICALLY CONTACTING INDIVIDUALLY SEPARATED DIES	HEDLER, HARRY
<u>10790907</u>	Not Issued	30	03/02/2004	Integrated circuit with re-route layer and stacked die assembly	HEDLER, HARRY
<u>10836143</u>	Not Issued	30	04/30/2004	Semiconductor device and method for fabricating the semiconductor device	HEDLER, HARRY
<u>10855891</u>	Not Issued	41	05/28/2004	Contact-connection device for electronic circuit units and production method	HEDLER, HARRY
<u>10900578</u>	Not Issued	30	07/28/2004	Semiconductor module and method for producing a semiconductor module	HEDLER, HARRY

10952383	Not Issued	30	09/29/2004	Method for producing a multichip module and multichip module	HEDLER, HARRY
10963434	Not Issued	30	10/12/2004	Electronic component with flexible contacting pads and method for producing the electronic component	HEDLER, HARRY
11008081	Not Issued	30	12/09/2004	Configuration having an electronic device electrically connected to a printed circuit board	HEDLER, HARRY


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Your Search was:

Last Name = HEDLER

First Name = HARRY

Application#	Patent#	Status	Date Filed	Title	Inventor Name
11030799	Not Issued	30	01/07/2005	Method of producing an electronic component	HEDLER, HARRY
11038465	Not Issued	30	01/21/2005	Semiconductor device	HEDLER, HARRY
11061762	Not Issued	19	02/22/2005	Semiconductor component having a CSP housing	HEDLER, HARRY
11086922	Not Issued	30	03/21/2005	Integrated device and electronic system	HEDLER, HARRY
11098780	Not Issued	30	04/04/2005	Stacked die package	HEDLER, HARRY
11124515	Not Issued	30	05/06/2005	Method of producing an electronic component with flexible bonding pads	HEDLER, HARRY
11126392	Not Issued	30	05/11/2005	Method of manufacturing a semiconductor device comprising stacked chips and a corresponding semiconductor device	HEDLER, HARRY
11137061	Not Issued	20	05/25/2005	Flexible contact-connection device	HEDLER, HARRY
11140687	Not Issued	30	05/31/2005	Manufacturing method for an electronic component assembly and corresponding electronic component assembly	HEDLER, HARRY
11153510	Not Issued	20	06/15/2005	Method for connecting an integrated circuit to a substrate and corresponding circuit arrangement	HEDLER, HARRY
11172083	Not Issued	20	06/30/2005	Semiconductor device with semiconductor components connected to one another	HEDLER, HARRY
11185472	Not Issued	19	07/20/2005	Method for connection of an integrated circuit to a substrate, and a corresponding circuit	HEDLER, HARRY

				arrangement	
<u>11195462</u>	Not Issued	19	08/02/2005	Method of manufacturing a semiconductor structure having a wafer through-contact and a corresponding semiconductor structure	HEDLER, HARRY

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Day : Wednesday

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PALM INTRANET
Inventor Name Search Result

Your Search was:

Last Name = MUFF

First Name = SIMON

Application#	Patent#	Status	Date Filed	Title	Inventor Name
09154484	6104615	150	09/16/1998	SEMICONDUCTOR COMPONENT ASSEMBLY	MUFF, SIMON
09401386	Not Issued	164	09/22/1999	SEMICONDUCTOR COMPONENT HAVING A THERMALLY CONDUCTIVE PLATE	MUFF, SIMON
09514265	6534345	150	02/28/2000	METHOD FOR MOUNTING A SEMICONDUCTOR CHIP ON A CARRIER LAYER AND DEVICE FOR CARRYING OUT THE METHOD	MUFF, SIMON
09771912	6798045	150	01/29/2001	LEAD FRAME, CIRCUIT BOARD WITH LEAD FRAME, AND METHOD FOR PRODUCING THE LEAD FRAME	MUFF, SIMON
09776951	Not Issued	92	02/05/2001	METHOD AND DEVICE FOR ADAPTING/TUNING SIGNAL TRANSIT TIMES ON LINE SYSTEMS OR NETWORKS BETWEEN INTEGRATED CIRCUITS	MUFF, SIMON
09793344	6434035	150	02/26/2001	MEMORY SYSTEM	MUFF, SIMON
10010164	Not Issued	161	11/13/2001	IC chip	MUFF, SIMON
10137511	6911732	150	04/30/2002	INTEGRATED CIRCUIT	MUFF, SIMON
10145579	6686764	150	05/14/2002	APPARATUS AND METHOD FOR REDUCING REFLEXIONS IN A MEMORY BUS SYSTEM	MUFF, SIMON
10149892	Not Issued	30	10/01/2004	Encasing arrangement for a semiconductor component	MUFF, SIMON

10152496	Not Issued	161	05/21/2002	Circuit board for memory components	MUFF, SIMON
10155847	Not Issued	161	05/24/2002	Arrangement of memory chip housings on a DIMM circuit board	MUFF, SIMON
10266322	6765302	150	10/08/2002	SEMICONDUCTOR MODULE HAVING A CONFIGURABLE DATA WIDTH OF AN OUTPUT BUS, AND A HOUSING CONFIGURATION HAVING A SEMICONDUCTOR MODULE	MUFF, SIMON
10345057	6783372	150	01/15/2003	APPARATUS FOR CONNECTING SEMICONDUCTOR MODULES	MUFF, SIMON
10675492	Not Issued	93	09/30/2003	METHOD FOR CALIBRATING SEMICONDUCTOR DEVICES USING A COMMON CALIBRATION REFERENCE AND A CALIBRATION CIRCUIT	MUFF, SIMON
10721787	Not Issued	71	11/26/2003	Semiconductor component and method for producing same	MUFF, SIMON
10772356	6894525	150	02/06/2004	METHOD AND DEVICE FOR TIME MEASUREMENT ON SEMICONDUCTOR MODULES EMPLOYING THE BALL-GRID-ARRAY TECHNIQUE	MUFF, SIMON
10797941	Not Issued	20	03/11/2004	Topology for providing clock signals to multiple circuit units on a circuit module	MUFF, SIMON
11126408	Not Issued	30	05/11/2005	Stacked semiconductor memory device	MUFF, SIMON
11172083	Not Issued	20	06/30/2005	Semiconductor device with semiconductor components connected to one another	MUFF, SIMON
11192335	Not Issued	19	07/29/2005	Semiconductor memory module and system	MUFF, SIMON

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